

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT						
NATURE OF CONVEYANCE:	ASSIGNMENT						
CONVEYING PARTY DATA							
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>HIROSHI NAKAMURA</td> <td>11/11/2013</td> </tr> <tr> <td>TOMOHIRO IGARASHI</td> <td>11/11/2013</td> </tr> </tbody> </table>		Name	Execution Date	HIROSHI NAKAMURA	11/11/2013	TOMOHIRO IGARASHI	11/11/2013
Name	Execution Date						
HIROSHI NAKAMURA	11/11/2013						
TOMOHIRO IGARASHI	11/11/2013						
RECEIVING PARTY DATA							
Name:	TAIYO YUDEN CO., LTD.						
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City:	Tokyo						
State/Country:	JAPAN						
Postal Code:	110-0005						
PROPERTY NUMBERS Total: 1							
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14077697</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14077697		
Property Type	Number						
Application Number:	14077697						
CORRESPONDENCE DATA							
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NAME OF SUBMITTER:	MAIKO KUWADA						
Signature:	/Maiko Kuwada/						
Date:	11/12/2013						

OP \$40.00 14077697

This document serves as an Oath/Declaration (37 CFR 1.63).

Total Attachments: 2

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**COMBINED DECLARATION AND ASSIGNMENT
FOR UTILITY APPLICATION**

**Title of
Invention**

HIGH FREQUENCY CIRCUIT MODULE

DECLARATION

As a below named inventor, I hereby declare that:

This declaration
is directed to:

- The attached application, or
- United States application or PCT international application
number _____ filed on _____.

The above-identified application was made or authorized to be made by me/us.

I/we have reviewed and understand the contents of the above-identified application, including the claims, as amended by any amendment specifically referred to above.

I/we acknowledge the duty to disclose to the United States Patent and Trademark Office all information known to me/us to be material to patentability as defined in 37 CFR 1.56, including for continuation-in-part applications, material information which became available between the filing date of the prior application and the national or PCT International filing date of the continuation-in-part application.

I/we believe that I am/we are the original inventor(s) or original joint inventor(s) of a claimed invention in the application.

I/we hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

ASSIGNMENT

WHEREAS, Taiyo Yuden Co., Ltd., a corporation of Japan, whose post office address is 16-20, Ueno 6-chome, Taiho-ku, Tokyo 110-0005, Japan, (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to issue upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from Assignee is hereby acknowledged, I/WE have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the Assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to Assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration,

communicate with Assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns.

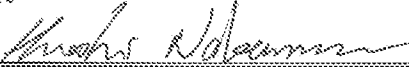
AND, I/WE HEREBY authorize and request the attorneys I/WE have empowered in the Power of Attorney in this application, to insert here in parenthesis (Application No. 14/077,697 , filed Nov. 12, 2013) the filing date and application number of said application when known.

IN TESTIMONY WHEREOF, I/WE have hereunto set our hand(s).

Legal Name of Sole or First Inventor

Hiroshi NAKAMURA

Signature



Date

Nov. 11 2013

Legal Name of Second Inventor

Tomohiro IGARASHI

Signature

Tomohiro IGARASHI

Date

Nov 11, 2013